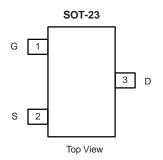
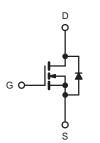


# K2569-VB Datasheet N-Channel 60-V (D-S) MOSFET

PRODUCT SUMMARY				
V <sub>DS</sub> (V)	$R_{DS(on)}$ ( $\Omega$ )	I <sub>D</sub> (mA)		
60	2.8 at V <sub>GS</sub> = 10 V	250		





N-Channel MOSFET

#### **FEATURES**

- Halogen-free According to IEC 61249-2-21 Definition
- Low Threshold: 2 V (typ.)
- Low Input Capacitance: 25 pF
- Fast Switching Speed: 25 ns
- Low Input and Output Leakage
- Trench Power MOSFET
- Compliant to RoHS Directive 2002/95/EC



RoHS\*

FREE Available

# **BENEFITS**

- · Low Offset Voltage
- Low-Voltage Operation
- Easily Driven Without Buffer
- High-Speed Circuits
- Low Error Voltage

#### **APPLICATIONS**

- Direct Logic-Level Interface: TTL/CMOS
- Drivers: Relays, Solenoids, Lamps, Hammers, Display, Memories, Transistors, etc.
- · Battery Operated Systems
- Solid-State Relays

ABSOLUTE MAXIMUM RATINGS T <sub>A</sub> = 25 °C, unless otherwise noted					
Parameter		Symbol	Limit	Unit	
Drain-Source Voltage		V <sub>DS</sub>	60	V	
Gate-Source Voltage		V <sub>GS</sub>	± 20	V	
Continuous Drain Current (T <sub>.I</sub> = 150 °C) <sup>b</sup>	T <sub>A</sub> = 25 °C	- I <sub>D</sub>	250	mA	
Continuous Diam Current (1) = 150 C)	T <sub>A</sub> = 100 °C	טי	150		
Pulsed Drain Current <sup>a</sup>		I <sub>DM</sub>	800		
Dower Dissipation	T <sub>A</sub> = 25 °C	$P_{D}$	0.30	W	
Power Dissipation <sup>b</sup>	T <sub>A</sub> = 100 °C	ט י	0.13	VV	
Maximum Junction-to-Ambient <sup>b</sup>		R <sub>thJA</sub>	350	°C/W	
Operating Junction and Storage Temperature Range		T <sub>J,</sub> T <sub>stg</sub>	- 55 to 150	°C	

#### Notes:

- a. Pulse width limited by maximum junction temperature.
- b. Surface Mounted on FR4 board.

<sup>\*</sup> Pb containing terminations are not RoHS compliant, exemptions may apply.



			Limits				
Parameter	Symbol	Test Conditions	Min.	Typ. <sup>a</sup>	Max.	Unit	
Static			•		•		
Drain-Source Breakdown Voltage	V <sub>DS</sub>	$V_{GS} = 0 \text{ V}, I_D = 10 \mu\text{A}$	60			V	
Gate-Threshold Voltage	V <sub>GS(th)</sub>	$V_{DS} = V_{GS}$ , $I_D = 250 \mu A$	1		2.5	V	
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	1		± 10		
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 15 \text{ V}$			1	μA	
Gate-Body Leakage	I <sub>GSS</sub>	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 10 \text{ V}$			± 150	nA	
		V <sub>DS</sub> = 0 V, V <sub>GS</sub> = ± 10 V, T <sub>J</sub> = 85 °C			± 1000		
		$V_{DS} = 0 \text{ V}, V_{GS} = \pm 5 \text{ V}$			± 100		
Zana Oata Valta va Basis Ourmant	,	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}$			1	μA	
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	$V_{DS} = 60 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 125 \text{ °C}$			500		
On-State Drain Current <sup>a</sup>	I <sub>D(on)</sub>	$V_{GS} = 10 \text{ V}, V_{DS} = 7.5 \text{ V}$	500 300			mA	
		$V_{GS} = 4.5 \text{ V}, V_{DS} = 10 \text{ V}$					
Drain-Source On-Resistance <sup>a</sup>	R <sub>DS(on)</sub>	$V_{GS} = 10 \text{ V}, I_D = 200 \text{ mA}$	2.8			Ω	
		$V_{GS} = 4.5 \text{ V}, I_D = 150 \text{ mA}$	3.1				
Forward Transconductance <sup>a</sup>	9 <sub>fs</sub>	V <sub>DS</sub> = 10 V, I <sub>D</sub> = 100 mA	100			mS	
Diode Forward Voltage	V <sub>SD</sub>	I <sub>S</sub> = 100 mA, V <sub>GS</sub> = 0 V			1.3	V	
Dynamic <sup>a</sup>					l		
Total Gate Charge	Qg	$V_{DS} = 10 \text{ V}, V_{GS} = 4.5 \text{ V}$ $I_{D} \cong 150 \text{ mA}$ 0.4		0.4	0.6	nC	
Input Capacitance	C <sub>iss</sub>			25		pF	
Output Capacitance	C <sub>oss</sub>	$V_{DS} = 25 \text{ V}, V_{GS} = 0 \text{ V}$		5			
Reverse Transfer Capacitance	C <sub>rss</sub>	f = 1 MHz		2.0			
Switching <sup>a, b, c</sup>	·				<u> </u>	1	
Turn-On Time	t <sub>d(on)</sub>	$V_{DD} = 30 \text{ V}, R_{L} = 150 \Omega$			20		
Turn-Off Time	t <sub>d(off)</sub>	$I_{D} \cong 200 \text{ mA}, V_{GEN} = 10 \text{ V}, R_{G} = 10 \Omega$			30	ns	

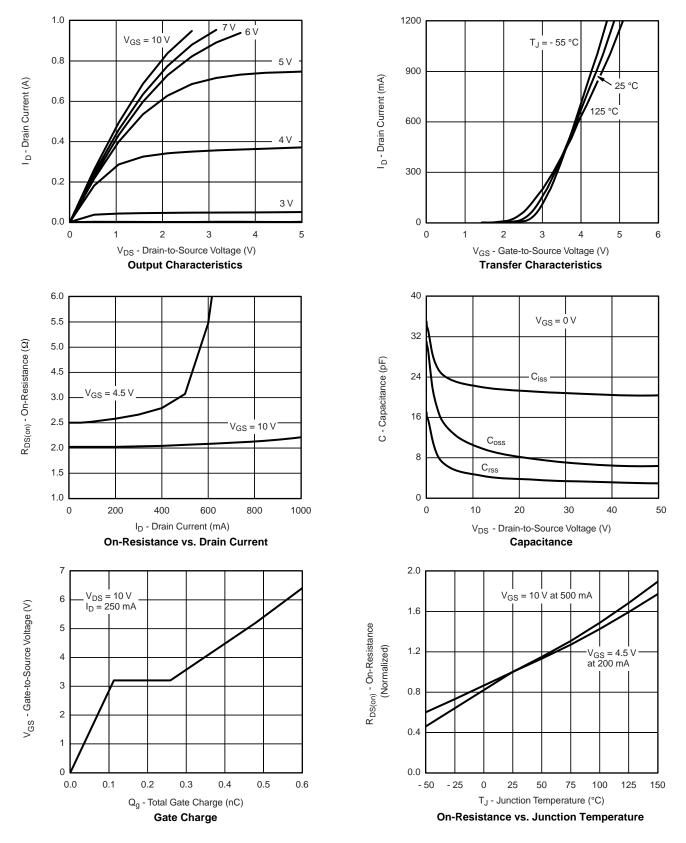
#### Notes:

- a. For DESIGN AID ONLY, not subject to production testing.
- b. Pulse test: PW  $\leq 300~\mu s$  duty cycle  $\leq 2~\%.$
- c. Switching time is essentially independent of operating temperature.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.



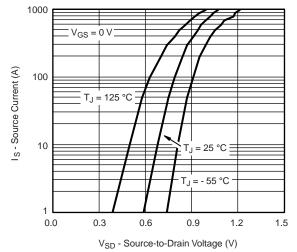
# TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

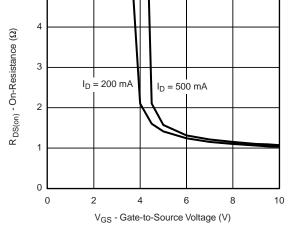


Normalized Effective Transient Thermal Impedance



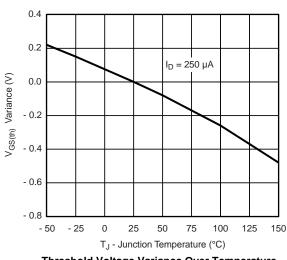
# TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

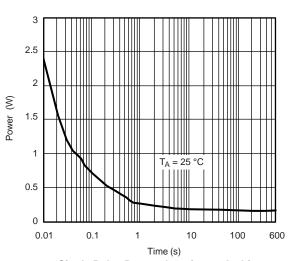




#### Source-Drain Diode Forward Voltage

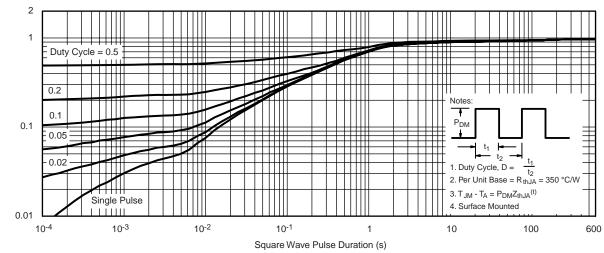






# **Threshold Voltage Variance Over Temperature**

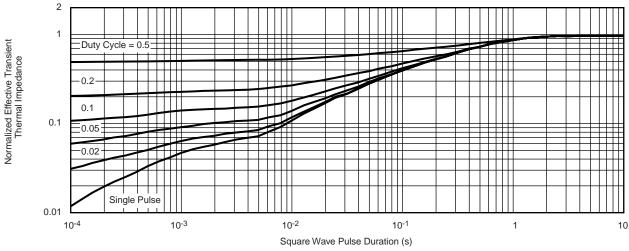
Single Pulse Power, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Ambient



# **THERMAL RATINGS** (T<sub>A</sub> = 25 °C, unless otherwise noted)



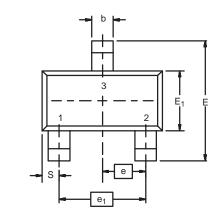
#### Normalized Thermal Transient Impedance, Junction-to-Foot

#### Note

- · The characteristics shown in the two graphs
- Normalized Transient Thermal Impedance Junction-to-Ambient (25 °C)
- Normalized Transient Thermal Impedance Junction-to-Foot (25 °C) are given for general guidelines only to enable the user to get a "ball park" indication of part capabilities. The data are extracted from single pulse transient thermal impedance characteristics which are developed from empirical measurements. The latter is valid for the part mounted on printed circuit board FR4, size 1" x 1" x 0.062", double sided with 2 oz. copper, 100 % on both sides. The part capabilities can widely vary depending on actual application parameters and operating conditions.



# SOT-23 (TO-236): 3-LEAD







Dim	MILLIMETERS		INCHES		
	Min	Max	Min	Max	
Α	0.89	1.12	0.035	0.044	
A <sub>1</sub>	0.01	0.10	0.0004	0.004	
A <sub>2</sub>	0.88	1.02	0.0346	0.040	
b	0.35	0.50	0.014	0.020	
С	0.085	0.18	0.003	0.007	
D	2.80	3.04	0.110	0.120	
E	2.10	2.64	0.083	0.104	
E <sub>1</sub>	1.20	1.40	0.047	0.055	
е	0.95 BSC		0.0374 Ref		
e <sub>1</sub>	1.90 BSC		0.0748 Ref		
L	0.40	0.60	0.016	0.024	
L <sub>1</sub>	0.64 Ref		0.025 Ref		
S	0.50 Ref		0.020 Ref		
q	3°	8°	3°	8°	
ECN: S-03946-Rev. K. 09-	Jul-01	•			

DWG: 5479



# **RECOMMENDED MINIMUM PADS FOR SOT-23**



Recommended Minimum Pads Dimensions in Inches/(mm)



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